10/672,494

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1110	(heat adj spreader) and chip$1 and cooling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:19
L2	410	1 and gap$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:19
L3	187	2 and (filler (thermally adj conductive adj material))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:20
L4	493	gap and (multichip multi-chip) and (filler (thermally adj conductive adj material))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:21
L5	596	gap$1 and (multichip multi-chip) and (filler (thermally adj conductive adj material))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:21
L6	316	5 and cooling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:22
L8	900	(361/717,718,708).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:22
L9	2906	(257/707,713,717).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:23

10/672,494

L10	935	(257/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:23
L11	2230	(257/713,717).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:23
L12	1096	(257/717).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:23
L13	1289	(257/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:24
L14	1037	(361/706,707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:24
L15	36	14 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:27
L16	10	14 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:27
L17	8	14 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:28

10/672,494

L18	0	17 not 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/17 17:28
L19	260	((361/717,718) or (257/707,713, 717)).CCLS.	US-PGPUB	OR	OFF	2005/11/17 17:29
L20	243	cooling and (heatspreader$1 (heat adj spreader$1)) and (chip$1 ic (integrated adj circuit$1)) and gap$1	US-PGPUB	OR	OFF	2005/11/17 17:32